To our customers,

Old Company Name in Catalogs and Other Documents

On April 1st, 2010, NEC Electronics Corporation merged with Renesas Technology Corporation, and Renesas Electronics Corporation took over all the business of both companies. Therefore, although the old company name remains in this document, it is a valid Renesas Electronics document. We appreciate your understanding.

Renesas Electronics website: http://www.renesas.com

April 1st, 2010
Renesas Electronics Corporation

Issued by: Renesas Electronics Corporation (http://www.renesas.com)

Send any inquiries to http://www.renesas.com/inquiry.

HITACHI SEMICONDUCTOR TECHNICAL UPDATE

DATE	5th July, 1999	No.	TN-SH7-171 A/E
THEME	HD6417750BP200 usage notice of reflow and storage conditions.		
CLASSIFICATION	☐ Spec. change ■ Supplement of Documents ■ Limitation on Use		
PRODUCT NAME	HD6417750BP200		
REFERENCE DOCUMENTS	SH4(SH7750) Hardware manual	Effective Date From	eternity

HD6417750BP200 have followed usage notice for reflow and storage conditions.

Although this product is supplied in a moisture resistant packaged condition, be sure to follow the conditions below when the package is heated to a high temperature using a method such as vapor phase reflow or repair. If not, package cracks or characteristics failure may occur.

(1) Storage time after opening the moisture resistant package for each reflow temperature.
(a) Reflow temperature(235℃ max)
Storage time after opening the moisture resistant package, use the LSI within 72hr.
(b) Reflow temperature(225℃ max)
Storage time after opening the moisture resistant package, use the LSI within 168hr.

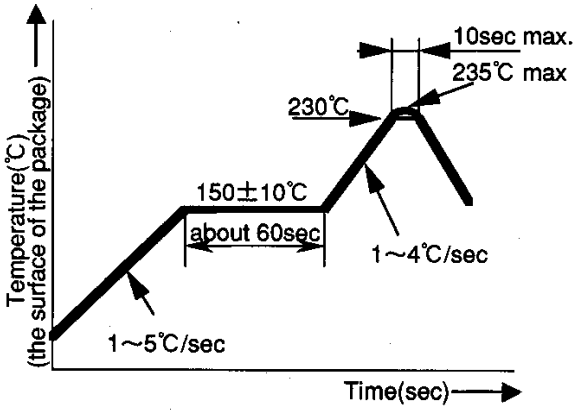
Storage condition
Temperature : Below 30℃
Humidity : Below 60%

(2) If the storage time exceeds "(1)", bake the LSI before soldering it with following conditions.

Baking conditions
125℃, 16～24hr, Power off
After baking, the time and the storage conditions until soldering are the same as (1).

(3) The recommended temperature at reflow time is shown in below.
The way to solder the LSI is infrared reflow or air reflow, or N2 reflow.

(a) Reflow temperature235℃ max



(b) Reflow temperature225℃ max